



## Material Content Data Sheet



Sales Product Name	TLE9266QX			Issued		28. August 2013		
MA#	MA001089750							
Package	PG-VQFN-48-31			Weight*		129.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.168	2.45	2.45	24459	24459
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		553	
	non noble metal	iron	7439-89-6	1.433	1.11		11066	
	non noble metal	copper	7440-50-8	58.193	44.94	46.12	449337	461094
wire	non noble metal	copper	7440-50-8	0.502	0.39	0.39	3875	3875
encapsulation	organic material	carbon black	1333-86-4	0.186	0.14		1436	
	plastics	epoxy resin	-	7.874	6.08		60797	
	inorganic material	silicondioxide	60676-86-0	53.938	41.65	47.87	416482	478715
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20048	20048
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4740	4740
glue	plastics	epoxy resin	-	0.211	0.16		1626	
	noble metal	silver	7440-22-4	0.705	0.54	0.70	5443	7069
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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